

SURFACE MOUNT TRANSIENT VOLTAGE SUPPRESSOR

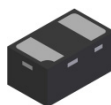
Features

- Planar Die Construction
- Ultra-Small Leadless Surface Mount Package
- Unidirectional
- Ideally Suited for Automated Assembly Processes
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 
- Weight: 0.001 grams (approximate)

X1-DFN1006-2



Bottom View

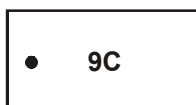
Ordering Information (Note 4)

Part Number	Case	Packaging
TPD6V8LP-7	X1-DFN1006-2	3000/Tape & Reel
TPD6V8LP-7B	X1-DFN1006-2	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

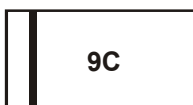
Marking Information

TPD6V8LP-7



Dot Denotes
Cathode Side

TPD6V8LP-7B



Bar Denotes
Cathode Side

9C = Product Type Marking Code

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Pulse Power ($t_p = 8 \times 20\mu\text{s}$) (Note 5) (See Figure 6)	P_{pk}	85	W
Forward Voltage (Note 6) @ $I_F = 10\text{mA}$	V_F	0.9	V
Peak Pulse Current ($t_p = 8 \times 20\mu\text{s}$) (Note 5) (See Figure 6)	I_{pp}	4.5	A
ESD Rating	Human Body Model	8	kV
	Machine Model	400	V
	IEC61000-4-2 Air Discharge	± 25	kV
	IEC61000-4-2 Contact Discharge	± 8	kV

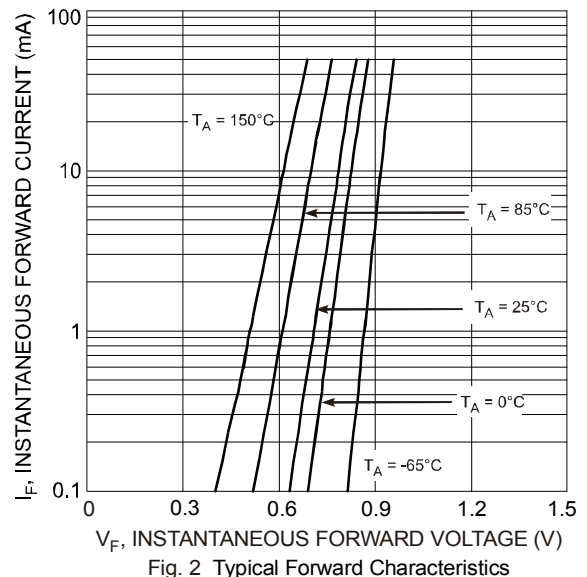
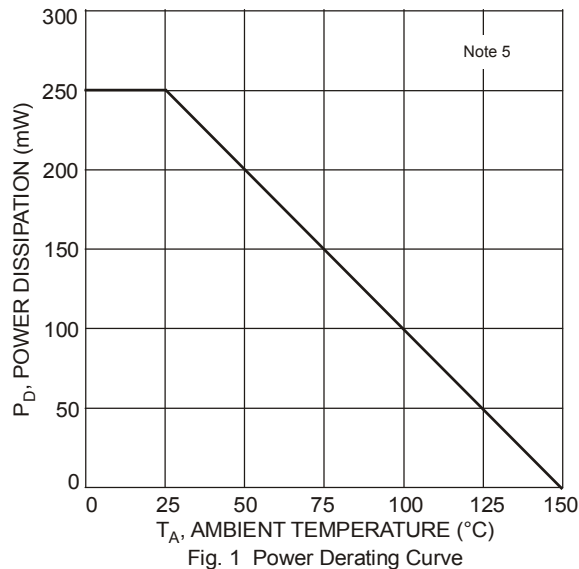
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	250	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{\theta JA}$	500	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Reverse Standoff Voltage	V_{RWM}	5	V
Breakdown Voltage @ $I_T = 5\text{mA}$ (Note 6)	V_{BR}	6.4	V
		7.2	
Maximum Reverse Leakage @ V_{RWM} (Note 6) @ V_R (Notes 6, 7)	I_R	0.5	μA
		380	nA
Maximum Clamping Voltage @ $I_{pp} = 4.5\text{A}$ ($t_p = 8 \times 20\mu\text{s}$) (See Figure 6)	V_C	19	V
Typical Total Capacitance ($V_R = 0\text{V}$, $f = 1\text{MHz}$)	C_T	65	pF

- Notes:
- Part mounted on FR-4 PC board with recommended pad layout, as per <http://www.diodes.com>.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed over the temperature range -40°C to $+85^\circ\text{C}$ and over the reverse voltage (V_R) range 2.0V to 2.6V.



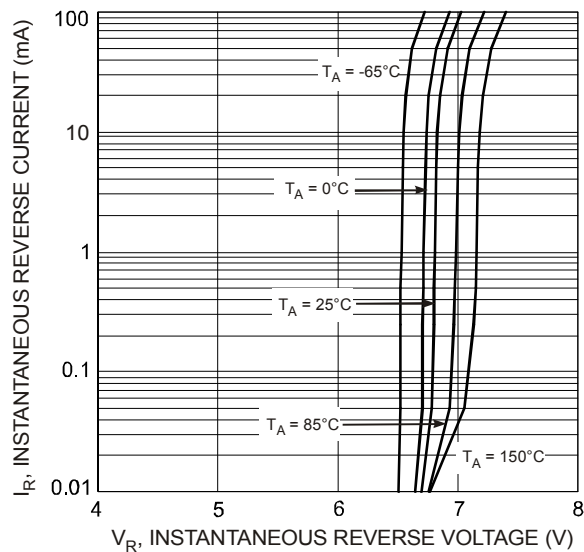


Fig. 3 Typical Breakdown Characteristics

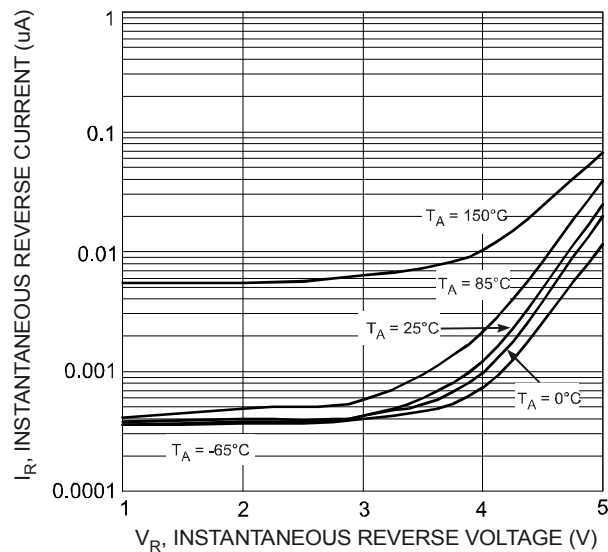


Fig. 4 Typical Low Current Reverse Characteristics

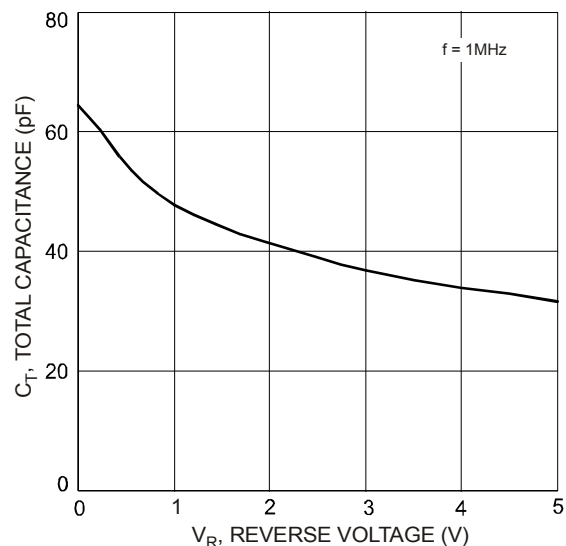


Fig. 5 Typical Total Capacitance vs. Reverse Voltage

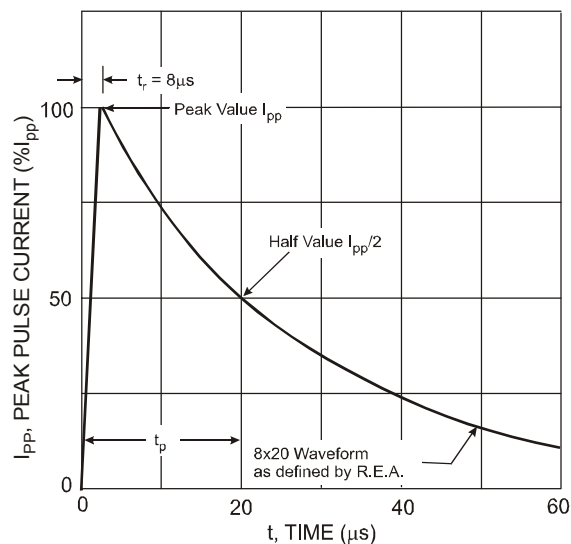
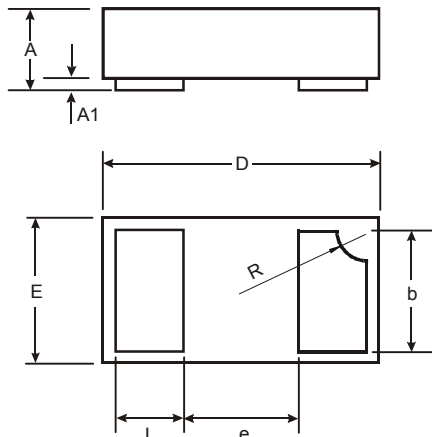


Fig. 6 Pulse Waveform

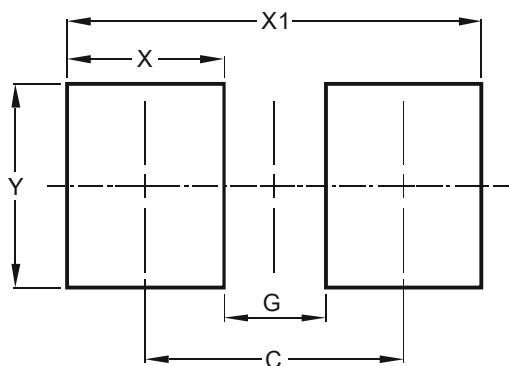
Package Outline Dimensions

 Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.


X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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